## ZNI1000 Temperature sensor

## Description

The ZNI1000 is a Ni thin film Resistance Temperature Detector (RTD), specified to DIN 43760. The high temperature coefficient offers higher signal outputs than other RTD's, which results in higher accuracy with smaller temperature changes.

## Features

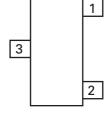
- Resistance at 0°C: 1000
- Nickel temperature detector
- Specified to DIN 43760
- SOT23 package

## Applications

- Automotive electronic
- Circuit protection
- Temperature compensation
- Temperature measurement

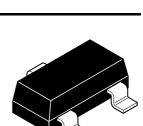
## **Ordering information**

Device	Reel size (inches)	Tape width (mm)	Quantity per reel	Device marking
ZNI1000TA	7	8	3,000	ZNI
ZNI1000TC	13	8	10,000	ZNI



Pinout - top view

Pin 1 - Ni1000 Pin 2 - Ni1000 Pin 3 - Need a good thermal contact for short response time





## Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Continuous current <sup>(a)</sup>	I <sub>CC</sub>	5	mA
Total power dissipation	P <sub>TOT</sub>	20	mW
Operating temperature range	T <sub>A</sub>	-55 to +150	°C
Storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### NOTES:

(a) Limited by operating temperature [  $I_{CC}{\leq}(20mW/R)^{\frac{1}{2}}$  , R=func(T\_A)=718 to 1986\Omega].

### **Recommended operating conditions**

Symbol	Parameter	Min.	Тур.	Max.	Unit
I <sub>MDC</sub>	Steady state measurement current <sup>(b)</sup>	0,1	1,2	3,0	mA

### NOTES:

(b) limited by self heating effects (recommended current range 0,1 to 1,5mA)

[ typ. case  $\rightarrow$  temperature error  $\Delta$ T= (R·1,2mA·1,2mA)/1,7mW/K  $\leq$  1,7K ]

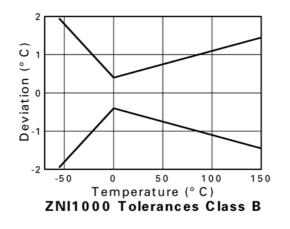
[ worst case → temperature error  $\Delta T$ = (1,986k $\Omega$ ·3,0mA·3,0mA)/1,4mW/K = 13,8K ].

### **Electrical characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R0	Resistance 0°C	T=0°C, I <sub>M</sub> <1mA	-	1000	-	Ω
R25	Resistance 25°C	T=25°C, $I_M = 3mA^{(c)}$	1100	1141	1200	Ω
R100	Resistance 100°C	T=100°C, I <sub>M</sub> <1mA	-	1618	-	Ω
	Tolerance class B <sup>(d)</sup>	-55 to 0°C	-	±(0.4+0.028 x ¦T¦)	-	°C
	Tolerance class B <sup>(d)</sup>	0 to 150°C	-	±(0.4+0.007 x ¦T¦)	-	°C
$\Delta R$	Long Term stability:	1000h at 150°C		0.1		%

### NOTES:

(c) Measured under pulse conditions.(d) See ZNi1000 Tolerance class figure.



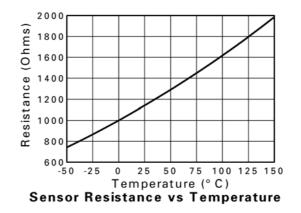
## **Characteristics according to DIN43760**

### Resistance at a given temperature

R0	Resistance at 0°C	В	6.650 x 10 <sup>-6</sup>
Т	Temperature in °C	С	2.805 x 10 <sup>-11</sup>

А	5.485 x 10 <sup>-3</sup>	D	-2.000 x 10 <sup>-17</sup>

$$R(T) = R0 \times (1 + A \times T + B \times T^{2} + C \times T^{4} + D \times T^{6})$$



### Formula for temperature at a given resistance

 $T(R) = A + B \times \sqrt{1 + C \times R} + D \times R^{5} + E \times R^{7}$ coefficients: A = -412.6B = 140.41C = 0.00764 $D = -6.25 \times 10^{-17}$  $E = -1.25 \times 10^{-24}$ 

### Self heating

For accurate temperature measurement it's recommended to choose a small current in order to avoid self heating of the resistor. The temperature failure caused by the measurement current can be calculated with:

$$\Delta \mathsf{T}=\mathsf{P}/\mathsf{E}\mathsf{K}$$

where  $P = I^2 * R$  is the heat power caused by the measurement current and EK is the self heating coefficient.

The self heating coefficient for the Ni1000-SOT is:

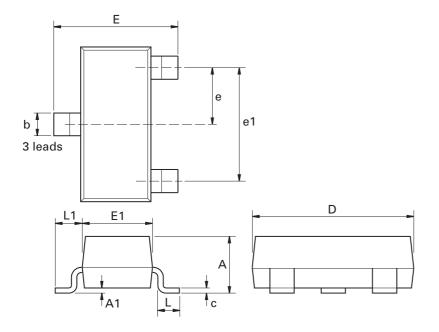
 $EK = (1.7 \pm 0.3) \text{ mW/K}$  (Air: 23°C; no air flow).

₽° C | DVM 1V-->100'C 0,2V-->20'C 0 Application of the nickel sensor ZNI 1000 500 680 1,5k ≒ 11 100n OUT 1,5k ZMR500 (5V) GND +ZNI1000 t° Ζ (1k) 10u + 100n

# ZNI1000

+15V

## Package outline - SOT23



Dim.	Millin	neters	Inc	hes	Dim.	Millin	neters	Inc	hes
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
А	-	1.12	-	0.044	e1	1.90	NOM	0.075	NOM
A1	0.01	0.10	0.0004	0.004	E	2.10	2.64	0.083	0.104
b	0.30	0.50	0.012	0.020	E1	1.20	1.40	0.047	0.055
С	0.085	0.20	0.003	0.008	L	0.25	0.60	0.0098	0.0236
D	2.80	3.04	0.110	0.120	L1	0.45	0.62	0.018	0.024
е	0.95	NOM	0.037	NOM	-	-	-	-	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

#### Definitions

### Product change

Zetex Semiconductors reserves the right to alter, without notice, specifications, design, price or conditions of supply of any product or service. Customers are solely responsible for obtaining the latest relevant information before placing orders.

### Applications disclaimer

The circuits in this design/application note are offered as design ideas. It is the responsibility of the user to ensure that the circuit is fit for the user's application and meets with the user's requirements. No representation or warranty is given and no liability whatsoever is assumed by Zetex with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Zetex does not assume any legal responsibility or will not be held legally liable (whether in contract, tort (including negligence), breach of statutory duty, restriction or otherwise) for any damages, loss of profit, business, contract, opportunity or consequential loss in the use of these circuit applications, under any circumstances.

#### Life support

Zetex products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Zetex Semiconductors plc. As used herein:

- A. Life support devices or systems are devices or systems which:
- 1. are intended to implant into the body
- or
- 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

#### Reproduction

The product specifications contained in this publication are issued to provide outline information only which (unless agreed by the company in writing) may not be used, applied or reproduced for any purpose or form part of any order or contract or be regarded as a representation relating to the products or services concerned.

### Terms and Conditions

All products are sold subjects to Zetex' terms and conditions of sale, and this disclaimer (save in the event of a conflict between the two when the terms of the contract shall prevail) according to region, supplied at the time of order acknowledgement.

For the latest information on technology, delivery terms and conditions and prices, please contact your nearest Zetex sales office.

### Quality of product

Zetex is an ISO 9001 and TS16949 certified semiconductor manufacturer.

To ensure quality of service and products we strongly advise the purchase of parts directly from Zetex Semiconductors or one of our regionally authorized distributors. For a complete listing of authorized distributors please visit: www.zetex.com/salesnetwork

## Zetex Semiconductors does not warrant or accept any liability whatsoever in respect of any parts purchased through unauthorized sales channels. ESD (Electrostatic discharge)

Semiconductor devices are susceptible to damage by ESD. Suitable precautions should be taken when handling and transporting devices. The possible damage to devices depends on the circumstances of the handling and transporting, and the nature of the device. The extent of damage can vary from immediate functional or parametric malfunction to degradation of function or performance in use over time. Devices suspected of being affected should be replaced.

#### Green compliance

Zetex Semiconductors is committed to environmental excellence in all aspects of its operations which includes meeting or exceeding regulatory requirements with respect to the use of hazardous substances. Numerous successful programs have been implemented to reduce the use of hazardous substances and/or emissions.

All Zetex components are compliant with the RoHS directive, and through this it is supporting its customers in their compliance with WEEE and ELV directives.

Product status key:	
"Preview"	Future device intended for production at some point. Samples may be available
"Active"	Product status recommended for new designs
"Last time buy (LTB)"	Device will be discontinued and last time buy period and delivery is in effect
"Not recommended for new designs"	Device is still in production to support existing designs and production
"Obsolete"	Production has been discontinued
Datasheet status key:	
"Draft version"	This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.
"Provisional version"	This term denotes a pre-release datasheet. It provides a clear indication of anticipated performance. However, changes to the test conditions and specifications may occur, at any time and without notice.
"Issue"	This term denotes an issued datasheet containing finalized specifications. However, changes to specifications may occur, at any time and without notice.

#### Zetex sales offices

Europe	Americas	Asia Pacific	Corporate Headquarters
Zetex GmbH Kustermann-park Balanstraße 59 D-81541 München Germany	Zetex Inc 700 Veterans Memorial Highway Hauppauge, NY 11788 USA	Zetex (Asia Ltd) 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong	Zetex Semiconductors plc Zetex Technology Park, Chadderton Oldham, OL9 9LL United Kingdom
Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com	Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com	Telephone: (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com

© 2007 Published by Zetex Semiconductors plc

Issue 5 - June 2007

© Zetex Semiconductors plc 2007